

| PCN no.: PCN-092 rev.1.2 | | Date: 2015-07-03 |
|---|--|---|
| Device affected: | | Device version / Build Code: |
| nRF51822-QFAA | | G00, G10, G20, G30 |
| nRF51822-CEAA | | Doo, D10, D20, D30 |
| nRF51822-QFAB | | Boo, B20 |
| Data sheet references: | Agreement reference: | Customers reference: |
| See Appendix 1 | N/A | N/A |
| | | |
| Impact: Does the change affect produ | <u>ct</u> : | |
| 1. Form No | Yes – describe: | |
| 2. Fit 🔀 No | Yes – describe: | |
| 3. Function No | Yes – describe: See | description below |
| 4. Quality or Reliability 🔲 No | Yes – describe: | |
| Classification of change | r 🔀 Major | |
| | | |
| Impact: Does the change affect contain | <u>ner</u> : | |
| 5. Form No | Yes – describe: | |
| 6. Fit No | Yes – describe: New | v reel MOQ for nRF51822-CEAA variant |
| 7. Function No | Yes – describe: | |
| 8. Quality or Reliability No | Yes – describe: | |
| Classification of change Minor | Major | |
| Description of change: | | |
| New revision of the ICs, with the follow | ing key improvements/changes: | |
| | 3 -1 1 3 | |
| Radio and CPU concurrency | | |
| | vel code. New versions of the Sol | nefits include reduced application latency and increased ftDevices include APIs to enable/disable this feature. Refer |
| 2. Improved power efficiency | | |
| 300 uA reduction in active curren | t for CPU executing code from fla | ish. |
| Improved buck DC/DC regulator. | The new DC/DC only supplies the | Radio. Optimizations include automatic management |
| | to enable/disable the feature) and | d improved power efficiency. Refer to the Product |
| 3. Improved start-up time for Po | ower on Reset (POR) module | |
| Optimized POR module to provide | le faster start-up time across the | whole supply range (1.8 to 3.6 V). |
| 4. Fixes of anomalies | | |
| The new IC revision includes a nu anomalies refer to the new nRF5: | | ed in nRF51822-PAN v2.4. For an updated list of |
| 5. New container options for the | e CSP package variants | |
| | | |
| | OQ changed from 3000 to 7000 2-CEAA-R7 with a MOQ of 1500 | |
| Refer to the Product Specification | n version 3.1 for more information | n. |
| All new features and changes in electric Specification version 3.1 and the nRF51 Appendix 1 lists all changes with refere | Reference Manual version 3.o. | sion are documented in the nRF51822 Product |
| | | |



Reason for change:

New features, bug fixes, and improvements of performance and power efficiency.

Consequences of change:

1. Hardware

None. New revisions are drop-in compatible with the current revisions.

2. Teleregulatory and Bluetooth certification

Reference designs nRF₅1822-DF (QFN) and nRF₅1822-CEAA-DF (CSP) pass all telecommunications regulatory bodies' requirements with the stated product changes with no discernible performance change. A reassessment of design performance due to applicable telecommunications regulatory requirements is required for any product not identical to the referenced designs.

Bluetooth QDIDs are valid for the new device versions *). Bluetooth RF PHY conformance reassessment is recommended for all designs not identical to the referenced designs.

3. Software

None. New revisions are software compatible with the current revisions including software workarounds for fixed anomalies.

To verify this, Nordic has carried out compatibility testing with the following software revisions:

- S110 v5.2.1, v6.2.1, and v7.1
- S120 V1.0.1
- nRF51 SDK v6.1 and v7.0

Note that the SDK v7.0 is compatible only with the new nRF51-DK and not the nRF51822-DK or nRF51822-EK.

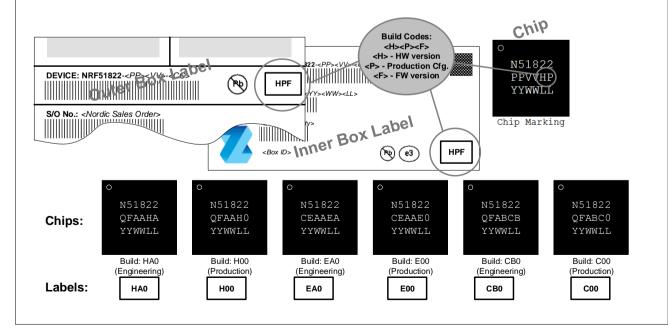
*) For more information on migrating to the new revisions refer to the white paper nWP-021 "Migrating from the 2nd to the 3rd revision of nRF51822", v.1.o.

Verification of change:

New revisions are approved and qualified under standard Nordic Semiconductor ASA QA procedures.

Marking/Shipping labels:

The new versions will be marked with new build codes as follows:





| Build code Hoo TSMC Fab1o / AMKOR ATP Now 2015-02-01 TSMC Fab1o / ASE ChungLi Now 2015-02-01 Hao TSMC Fab2 / AMKOR ATP To be announced Samples + 90 days H30 TSMC Fab3 / ASE ChungLi To be announced Samples + 90 days Now 2015-02-01 H30 TSMC Fab3 / ASE ChungLi To be announced Samples + 90 days NRF51822-CEAA (3.5x3.8mm CSP, 256kB Flash) Build Wafer / assembly Samples / reports Active from code Eoo TSMC Fab1o / Deca Now 2015-02-01 TECHNOlogies Second source build codes: E10 TSMC Fab1o / ASE ChungLi Now 2015-09-01 E20 TSMC Fab1o / ASE ChungLi To be announced Samples + 90 days TECHNOlogies To be announced Samples + 90 days NRF51822-QFAB (6x6mm QFN, 128kB Flash) Build Wafer / assembly Samples / reports Active from code Code TSMC Fab1 / ASE ChungLi Now 2015-02-01 RRF51822-QFAB (6x6mm QFN, 128kB Flash) Build Wafer / assembly Samples / reports Active from code Cod TSMC Fab10 / ASE ChungLi Now 2015-02-01 Second source build codes: C10 TSMC Fab2 / ANEC Fab10 / To be announced Samples + 90 days Second source build codes: C20 TSMC Fab2 / ANEC Fab10 / ASE ChungLi To be announced Samples + 90 days Second source build codes: C30 TSMC Fab2 / ANEC FATP To be announced Samples + 90 days Oote that the above 'active from' dates refer to the earliest date Nordic will fulfill orders with the new revisions instead of the order that a surface of the second source build codes, Nordic will update this PCN when the exact schedule of production samples and qualificate port are available. Ordic may on a limited basis support earlier ramp-up on the new revisions. Please contact Nordic sales for more informatic ast time order: Final shipment date: 2015-12-31 2016-06-30 Waw.nordicsemi.com, "Contact Us" www.nordicsemi.com, "Contact Us" www.nordicsemi.com, "Contact Us" | | nRF | 51822-QFAA (6x6mm | QFN, 256kB Flash) | | |
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Product Manager Date: 2015-07-03 Sign: Thomas E. B.

Quality Director Date: 2015-07-03 Sign:

Meg

Please note that all last time buy orders are non-cancellable and non-returnable.

| Revision History | | | | | |
|------------------|--|-------------------------|--|--|--|
| Revision | Date | Author | Comment | | |
| 1.0 | 2014-10-28 | T. Bonnerud | Initial Release | | |
| 1.1 | 2015-04-31 T. Bonnerud Updated build codes for nRF51822-QFAB | | | | |
| 1.2 | 2015-07-03 | D. Angco T. Bonnerud | Updated Active From dates for nRF51822-QFAA H10, nRF51822-CEAA E10 & nRF51822-QFAB C10. Added Last time order and final shipment date. | | |

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Appendix 1

Product change summary

This is a summary of the changes implemented in the relevant product documentation:

| Module | nRF51 Series Reference Manual v3.0 chapter | nRF51822 PS v3.1 chapter | Part changed/added | Comment | | | |
|------------------------|---|--------------------------------|--------------------------|--|--|--|--|
| RAM | 5.1.4 | 3.2.2 | RAM organization | The RAM is divided into multiple RAM AHB slaves. Added description on how to organize usages of the RAM to take advantages of multiple RAM AHB slaves. | | | |
| Power | 12.1.1 | 3.4.1 | Power Supply | Changed how the DC/DC and Regulators are organized. The DC/DC converter is only controlling the radio voltage. | | | |
| | 12.1.3 | 3.4.1.2 | DC/DC Converter setup | Improved the DC/DC solution: Simplified how the DC/DC is controlled and operates. Removed the complexity around how it is controlled. Removed the startup time issue. | | | |
| | 12.1.7 | 3.4.2.2 | System ON mode | Improved description around Low Power and Constant Latency | | | |
| | 12.1.12 | | Power-on reset | The Power-on reset module has been improved on the startup time for the whole VDD range (1.8 to 3.6 V). No change in the descriptive text but it's seen on the numbers specified for the Power-on reset module below. Both in chapter 7 Operation condition and section 8.2 Power Management. | | | |
| Timer | | 4.2 | Timer/ Counter | Added description about 1 MHz mode. | | | |
| Radio | 17.1.3 | | Maximum packet length | Correction of documentation error. No change in actual performance between current revision and new revisions. The combined length of SO, LENGTH, S1, and PAYLOAD is changed from "cannot exceed 255 bytes" to "cannot exceed 254 bytes". | | | |
| | 29.6 | | UART | New section "Suspending the UART" | | | |
| | 33 | | Software Interrupts | New chapter | | | |
| Operating Condition | | 7 | Table 20 | Parameter t _{R_VDD} is specified under new conditions to reflect the improved POR module. Old parameter description: <i>Supply rise time</i> (0V to 1.8 V) New parameter description: <i>Supply rise time</i> (0 V to VDD) | | | |
| | | | | $\begin{tabular}{ c c c c c c c c c c c c c c c c c c c$ | | | |
| System | | 8 | Electrical specification | Changes in the electrical specification | | | |
| | | 8.1.2 | Table 22 | Symbol Old value New Units value | | | |
| | | | | I _{X16M.1M} New par. 250 μA | | | |
| | | 8.1.3 | Table 23 | Symbol Old value New Units value | | | |
| | | | | I _{X32M,1M} | | | |



IORDICMICONDUCTOR Product Change Notification (PCN)

| Module | nRF51 Series Reference Manual v3.0 chapter | nRF51822 PS v3.1 chapter | Part changed/added | Comment | | | |
|--------|---|--------------------------------|----------------------|--|---|--------------------|----------|
| | | 8.1.4 | Table 24 | Symbol | Old value | New | Units |
| | | | | T | Managa | value 540 | 4 |
| | | | | $\begin{array}{ c c c c c }\hline I_{RC16M.1M} \\ \hline t_{START,RC16M} & (Typ.) \end{array}$ | New par. 2,5 | 4,2 | μA μs |
| | | | | t _{START,RC16M} (Max.) | 3,5 | 5,2 | μs |
| | | | | Correction of documenta performance between cur | tion error. No cl | hange in actu | ıal |
| | | 8.1.6 | Table 26 | Symbol | Old value | New value | Units |
| | | | | t _{START,RC32k} (Typ.) | 100 | 390 | μs |
| | | | | t _{START,RC32k} (Max.) | New par. | 487 | μs |
| | | | | Correction of documenta | | | |
| | | | | performance between cur | rent revision an | d new revisio | ons. |
| | | 8.1.7 | Table 27 | Symbol | Old value | New value | Units |
| | | | | t _{START,SYNT32k} | 100 | 406 | μs |
| | | | | Correction of documenta performance between cur | | | |
| | | 8.2 | Power management | The POR module is impro for the whole VDD range | oved so that it gives a fast startup time (1.8 to 3.6 V). | | |
| | | 8.2 | Table 30 | Symbol | Old value | New value | Units |
| | | | | t _{POR, 1µs} (Min, Typ) | Removed. | , | |
| | | | | t _{POR, 50ms} (Min, Typ) | Removed. | | |
| | | | | t _{POR, 10µs} (Min.) | New par. | 0,7 | ms |
| | | | | $t_{POR, 10\mu s}$ (Typ.) | New par. | 2.4 | ms |
| | | | | t _{POR, 10μs} (Max.) | New par. | 19 | ms |
| | | | | t _{POR, 1ms} (Min.) | New par. New par. | 1,7 3.4 | ms |
| | | | | $\begin{array}{ccc} t_{POR, 1ms} & (Typ.) \\ \hline t_{POR, 1ms} & (Max.) \end{array}$ | New par. | 20 | ms ms |
| | | | | t _{POR, 10ms} (Min.) | New par. | 11 | ms |
| | | | | t _{POR, 10ms} (Typ.) | New par. | 12 | ms |
| | | | | t _{POR, 10ms} (Max.) | New par. | 28 | ms |
| | | | | t _{POR, 100ms} (Min.) | New par. | 68 | ms |
| | | | | t _{POR, 100ms} (Typ.) | New par. | 101 | ms |
| | | | | t _{POR} , 100ms (Max.) | New par. | 115 | ms |
| | | | Table 32 | Symbol | Old value | New value | Units |
| | | | | I _{1V2XO16,1M} | New par. | 520 | μA |
| | | | | I _{1V2XO32,1M} | New par. | 560 | μΑ |
| | | | | I _{1V2RC16,1M} | New par. | 630 | μA |
| | | | | $\begin{array}{ c c c }\hline t_{XO} & (Typ.) \\\hline t_{XO} & (Max.) \end{array}$ | New par. New par. | 2,3 5,3 | μs |
| | | | | I_{DCDC} (Max.) | Removed | ٠,5 | μs |
| | | | | t _{START,DCDC} | Removed | | |
| | | 8.3 | Table 33 | Updated. Added row "CP | | mn " 1V7" . | |
| | | 8.4 | Table 34 | Symbol | Old value | New value | Units |
| | | | | I _{CPU,FLASH} | 4,4 | 4,1 | mA |
| | | 8.5.3 | Table 37 / Figure 11 | New section specifying R enabled. | adio parameters | s when the D | C/DC is |



RDICONDUCTOR Product Change Notification (PCN)

| Module | nRF51 Series Reference Manual v3.0 chapter | nRF51822 PS v3.1 chapter | Part changed/added | Comment | | | | |
|--------|---|--------------------------------|--------------------|---|--------------------------|----------------|-----------|--|
| | | | | New table 37 specifying the Radio current consumption when the DC/DC is enabled. Figure 11 gives the Conversion factor (F_{DCDC}) as function of VDD for selected radio modes. | | | | |
| | | 8.5.6 | Table 40 | Symbol t _{RXCHAIN} (250 k) | Old value 12 2 | New value 12,5 | Units µs | |
| | | | | t _{RXCHAIN} (1 M) 2 3 µs t _{RXCHAIN} (2 M) 2,5 2 µs Correction of documentation error. No change in actual performance between current revision and new revisions. | | | | |
| | | 8.7 | Table 43 | Symbol | Old value | New value | Units | |
| | | | | t _{CTSH} | New par. | 1 | μs | |
| | | 8.8 | Table 45 | Symbol | Old value | New value | Units | |
| | | | | t _{CD} 60 97 ns Correction of documentation error. No change in actual performance between current revision and new revisions. | | | | |
| | | 8.13 | Table 52 | Symbol | Old value | New value | Units | |
| | | | | I _{TIMER0/1/2,1M} | New par. | 4 | μΑ | |
| | | 8.15 | Table 54 | Improved the accuracy of the temperature sensor. Added a Note on T_{ACC} specifying that the accuracy is applicable in the range from 0°C to +60°C. | | | | |
| | | 8.22 | | Corrected the timing spec | cification for the | e NVMC mod | ule. | |
| | | | Table 61 | Symbol | Old value | New value | Units | |
| | | | | t _{ERASEALL} (Typ.) t _{ERASEALL} (Max.) t _{PAGEERASE} (Typ.) | Removed New par. Removed | 22.3 | ms | |
| | | | | t _{PAGEERASEALL} (Max.) | New par. | 22.3 | ms | |
| | | | | t _{WRITE} (Typ.) t _{WRITE,FLASH} (Max.) | Removed New par. | 46,3 | μs | |
| | | | | t _{WRITE,RAM,1st} (Max.) | New par. | 39,3 | μs | |
| | | | | t _{WRITE,RAM,2nd} (Max.) | New par. | 22,3 | μs | |
| | | | | t _{WRITE,RAM,3rd} (Max.) | New par. | 46,3 | μs | |
| | | 8.24 | Table 63 | Symbol | Old value | New value | Units | |
| | | | | t _{LPCOMPSTARTUP} | New par. | 40 | μs | |